

# TM06G04S

## N+P-Channel Enhancement Mode Mosfet

### General Description

- Low  $R_{DS(ON)}$
- RoHS and Halogen-Free Compliant

### Applications

- Load switch
- PWM

### Product Summary

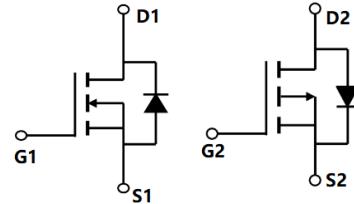
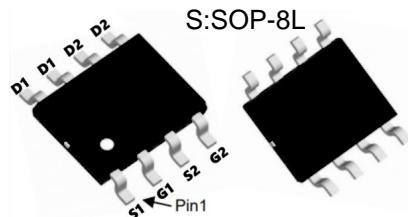
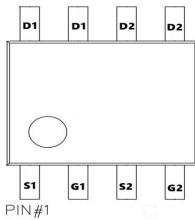
#### N Channel

$V_{DS} = 40V, I_D = 6.3A$   
 $R_{DS(ON)} = 30m\Omega$  (typ.) @  $V_{GS} = 10V$

#### P Channel

$V_{DS} = -40V, I_D = -6.1A$   
 $R_{DS(ON)} = 68m\Omega$  (typ.) @  $V_{GS} = -10V$

100% UIS Tested  
 100%  $R_g$  Tested



Marking: 06G04 OR 4614C

### Absolute Maximum Ratings ( $T_c = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating		Units
		N-Ch	P-Ch	
$V_{DS}$	Drain-Source Voltage	40	-40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	$\pm 20$	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	6.3	-6.1	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	4.9	-3.8	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	23	-22	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	16.2	39	mJ
$I_{AS}$	Avalanche Current	6.8	-6.8	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation <sup>4</sup>	1.67	1.67	W
$T_{STG}$	Storage Temperature Range	-55 to 150	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	-55 to 150	°C
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	75		°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	30		°C/W

**TM06G04S**
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**N-Channel Electrical Characteristics ( $T_J=25^{\circ}\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	40	44	---	V
$\Delta BVDSS/\Delta T_J$	BVDSS Temperature Coefficient	Reference to $25^{\circ}\text{C}$ , $I_D=1\text{mA}$	---	0.032	---	$\text{V}/^{\circ}\text{C}$
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10\text{V}$ , $I_D=4\text{A}$	---	30	39	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=3\text{A}$	---	40	48	
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250\mu\text{A}$	1.5	2.5	3.5	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	-4.5	---	$\text{mV}/^{\circ}\text{C}$
IDSS	Drain-Source Leakage Current	$V_{DS}=32\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25^{\circ}\text{C}$	---	---	1	$\mu\text{A}$
		$V_{DS}=32\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=55^{\circ}\text{C}$	---	---	5	
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	nA
gfs	Forward Transconductance	$V_{DS}=5\text{V}$ , $I_D=4\text{A}$	---	8	---	S
R <sub>g</sub>	Gate Resistance	$V_{DS}=0\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	2.4	4.8	$\Omega$
Q <sub>g</sub>	Total Gate Charge (4.5V)	$V_{DS}=15\text{V}$ , $V_{GS}=4.5\text{V}$ , $I_D=3\text{A}$	---	5	---	nC
Qgs	Gate-Source Charge		---	1.54	---	
Qgd	Gate-Drain Charge		---	1.84	---	
Td(on)	Turn-On Delay Time	$V_{DD}=15\text{V}$ , $V_{GS}=10\text{V}$ , $R_G=3.3\text{k}\Omega$ $I_D=1\text{A}$	---	7.8	---	ns
T <sub>r</sub>	Rise Time		---	2.1	---	
Td(off)	Turn-Off Delay Time		---	29	---	
T <sub>f</sub>	Fall Time		---	2.1	---	
Ciss	Input Capacitance	$V_{DS}=15\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	452	---	pF
Coss	Output Capacitance		---	51	---	
Crss	Reverse Transfer Capacitance		---	38	---	
IS	Continuous Source Current <sup>1,4</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	6.3	A
ISM	Pulsed Source Current <sup>2,4</sup>		---	---	14	A
VSD	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0\text{V}$ , $I_S=1\text{A}$ , $T_J=25^{\circ}\text{C}$	---	---	1.2	V

**Note :**

- 1、The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3、The power dissipation is limited by  $150^{\circ}\text{C}$  junction temperature
- 4、The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

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**P-Channel Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=-250\mu\text{A}$	-40	-44	---	V
$\Delta BVDSS/\Delta T_J$	$BVDSS$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=-1\text{mA}$	---	-0.018	---	$\text{V}/^\circ\text{C}$
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=-10\text{V}$ , $I_D=-3\text{A}$	---	68	78	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$ , $I_D=-2\text{A}$	---	78	98	
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=-250\mu\text{A}$	-1.5	-2.5	-3.5	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	2.5	---	$\text{mV}/^\circ\text{C}$
IDSS	Drain-Source Leakage Current	$V_{DS}=-40\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	-1	$\text{uA}$
		$V_{DS}=-40\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	-5	
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm20\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm100$	nA
gfs	Forward Transconductance	$V_{DS}=-5\text{V}$ , $I_D=-3\text{A}$	---	5.8	---	S
Qg	Total Gate Charge (-4.5V)	$V_{DS}=-32\text{V}$ , $V_{GS}=-4.5\text{V}$ , $I_D=-3\text{A}$	---	6.4	---	nC
Qgs	Gate-Source Charge		---	2.1	---	
Qgd	Gate-Drain Charge		---	2.5	---	
Td(on)	Turn-On Delay Time	$V_{DD}=-20\text{V}$ , $V_{GS}=-4.5\text{V}$ , $R_G=3.3\Omega$ , $I_D=-3\text{A}$	---	4.2	---	ns
Tr	Rise Time		---	23	---	
Td(off)	Turn-Off Delay Time		---	26.8	---	
Tf	Fall Time		---	20.6	---	
Ciss	Input Capacitance	$V_{DS}=-15\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	620	---	pF
Coss	Output Capacitance		---	65	---	
Crss	Reverse Transfer Capacitance		---	53	---	
IS	Continuous Source Current <sup>1,4</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	-3.2	A
ISM	Pulsed Source Current <sup>2,4</sup>		---	---	-6.1	A
VSD	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0\text{V}$ , $I_S=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1	V

**Note :**

- 1、The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3、The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 4、The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

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### N+P-Channel Enhancement Mode Mosfet

#### N-Typical Characteristics

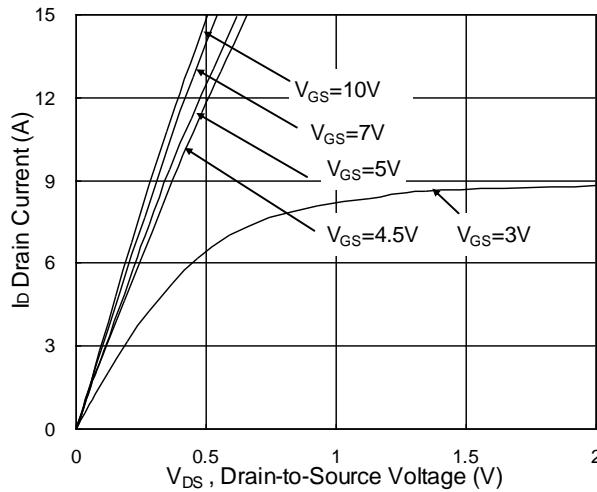


Fig.1 Typical Output Characteristics

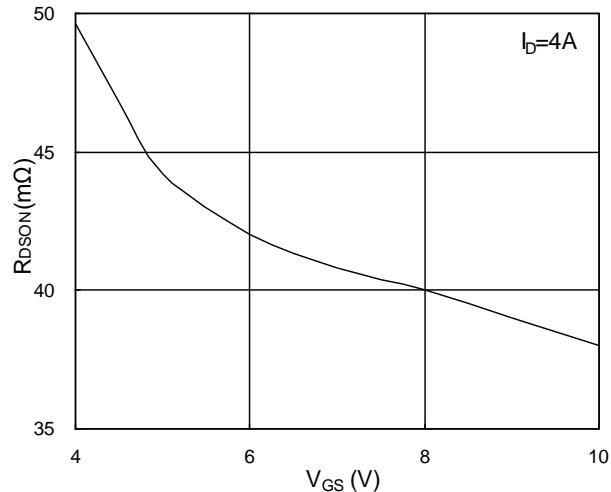


Fig.2 On-Resistance vs. Gate-Source

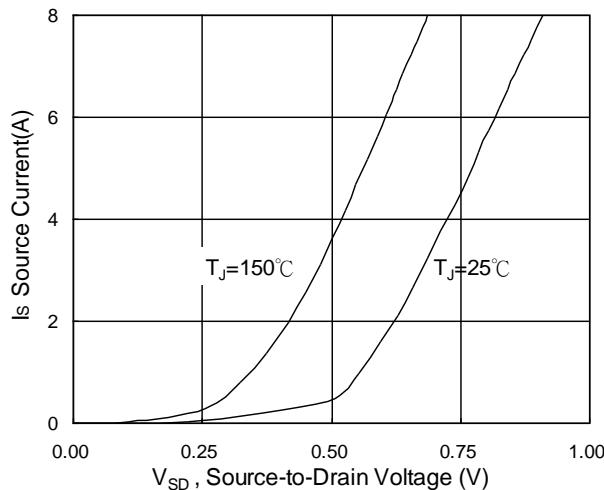


Fig.3 Forward Characteristics Of Reverse

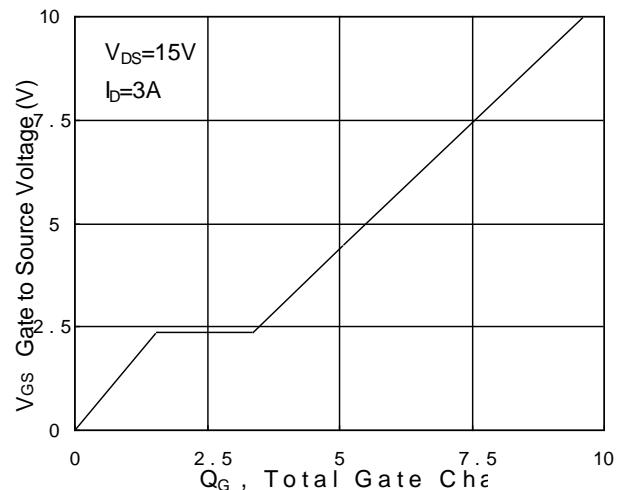


Fig.4 Gate-Charge Characteristics

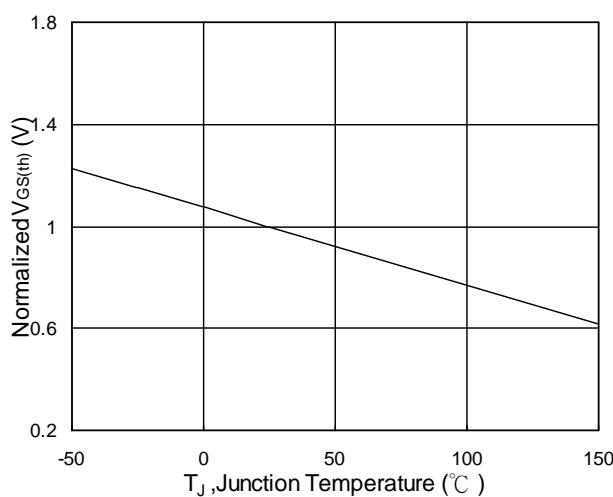


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

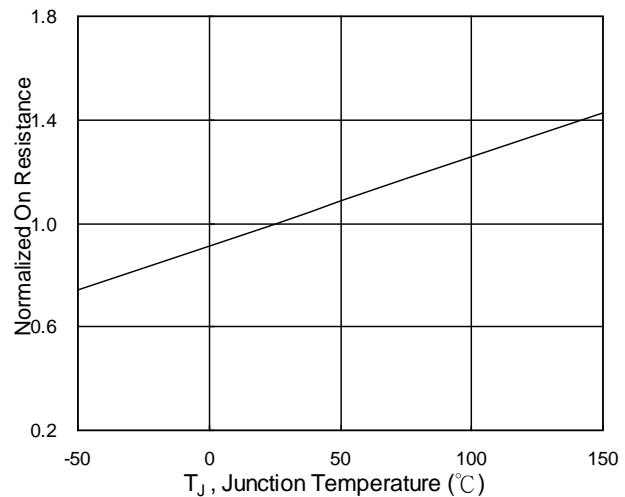
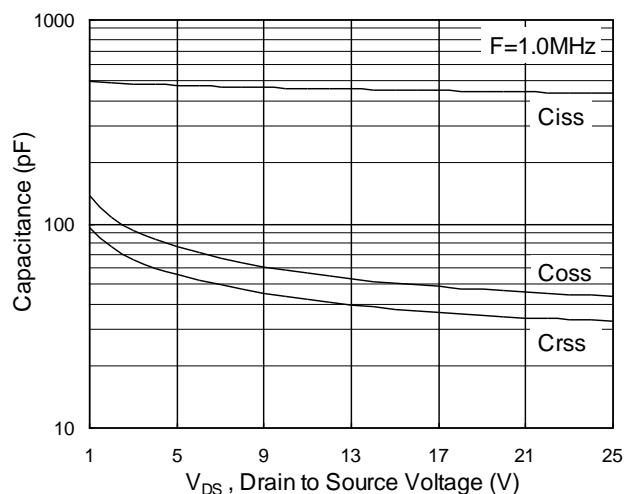


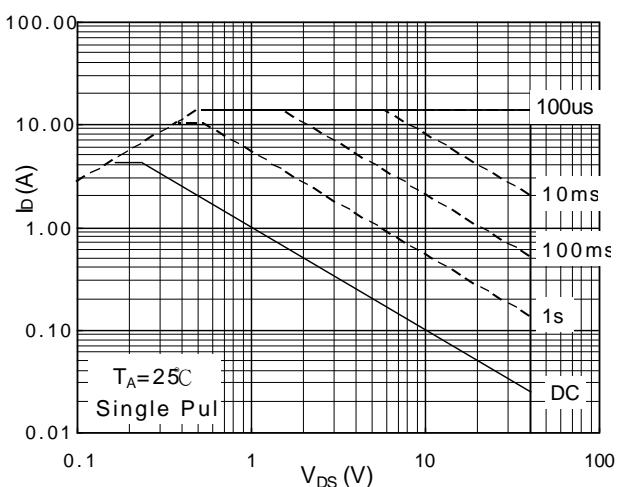
Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

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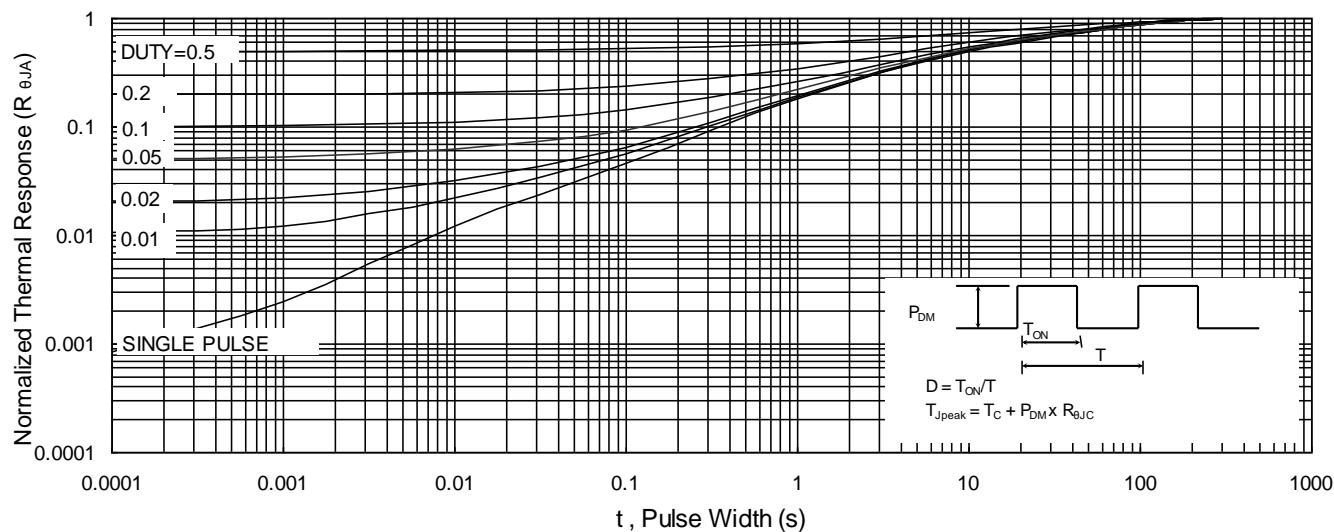
### N+P-Channel Enhancement Mode Mosfet



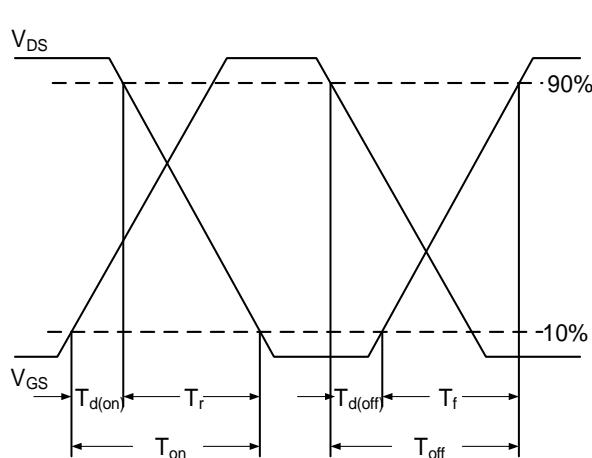
**Fig.7 Capacitance**



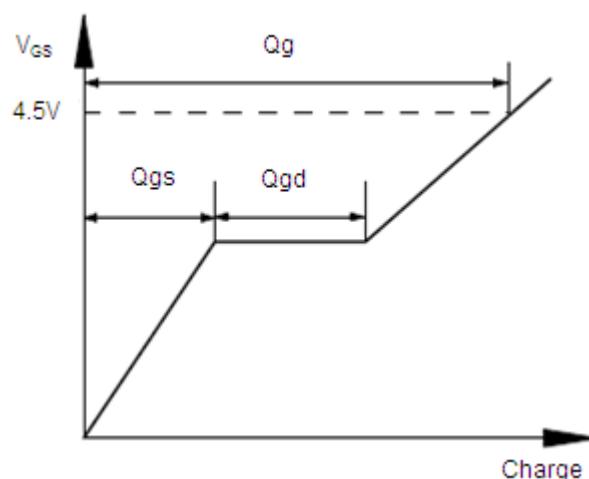
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



**Fig.11 Gate Charge Waveform**

## TM06G04S

## N+P-Channel Enhancement Mode Mosfet

### P-Typical Characteristics

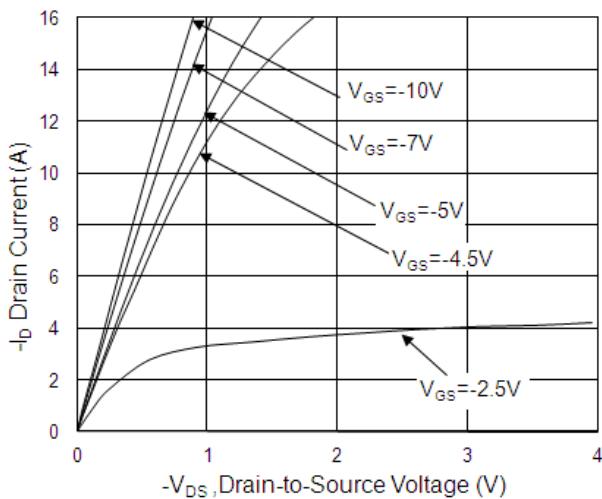


Fig.1 Typical Output Characteristics

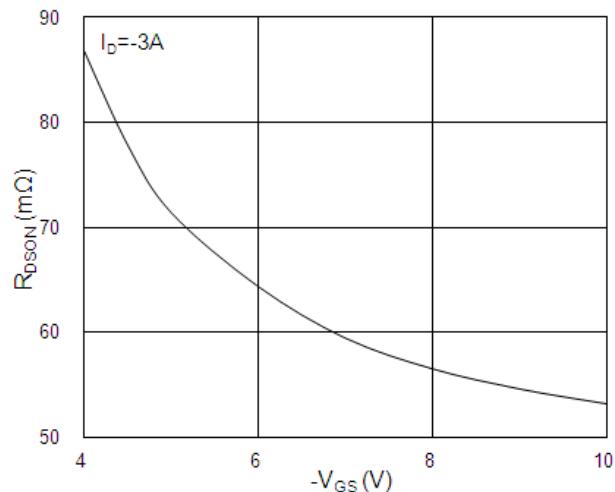


Fig.2 On-Resistance vs. G-S Voltage

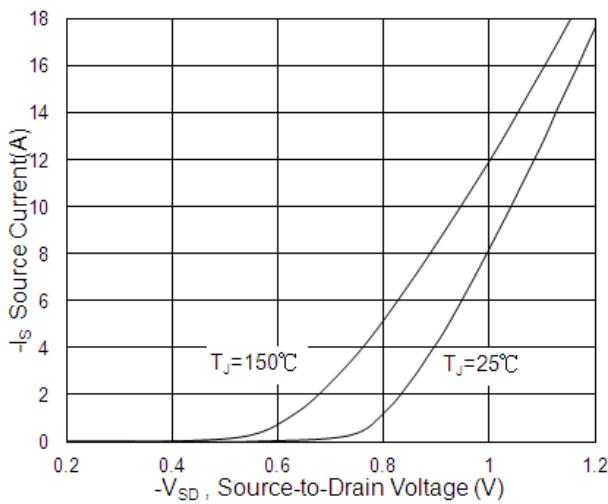


Fig.3 Forward Characteristics Of Reverse

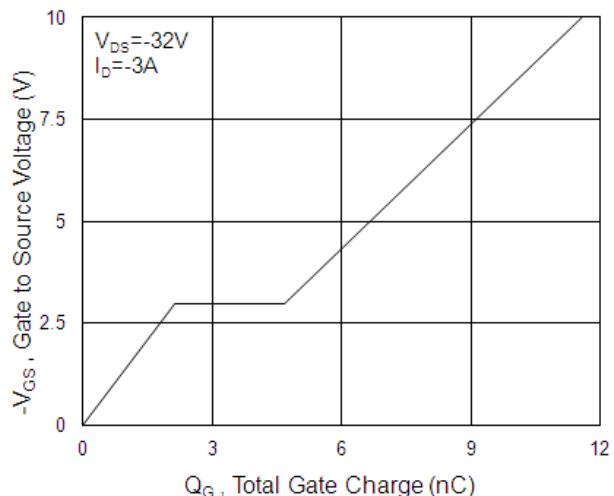


Fig.4 Gate-Charge Characteristics

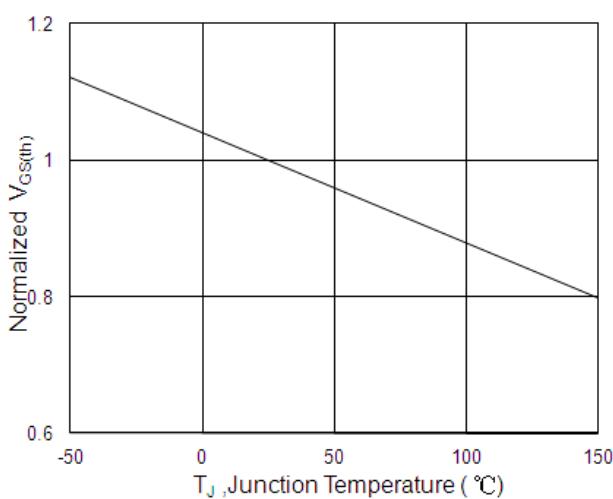


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

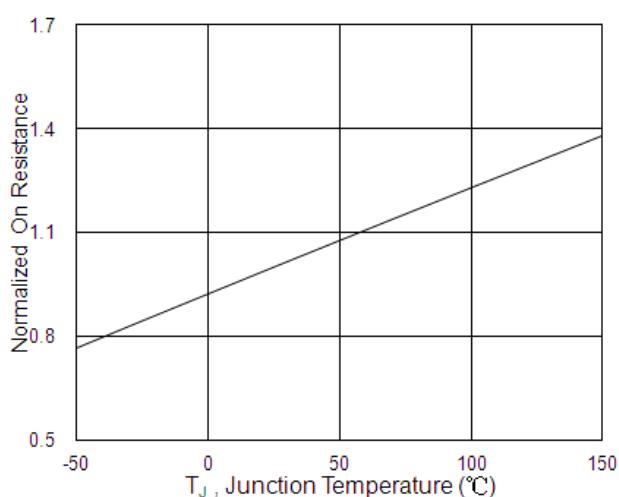
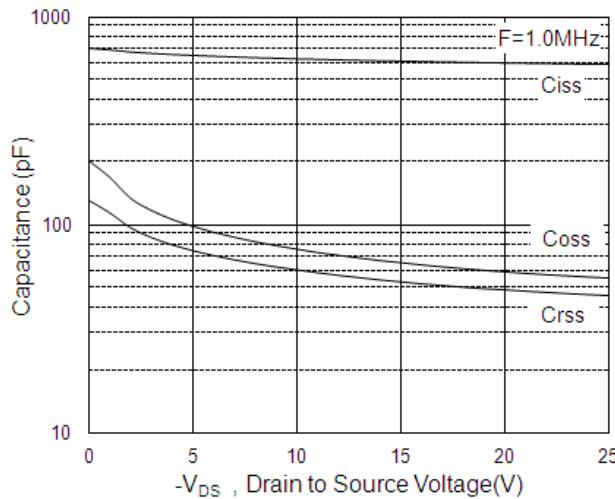


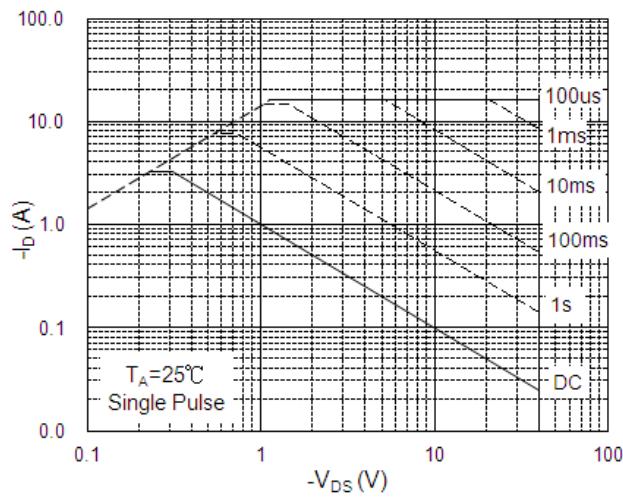
Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

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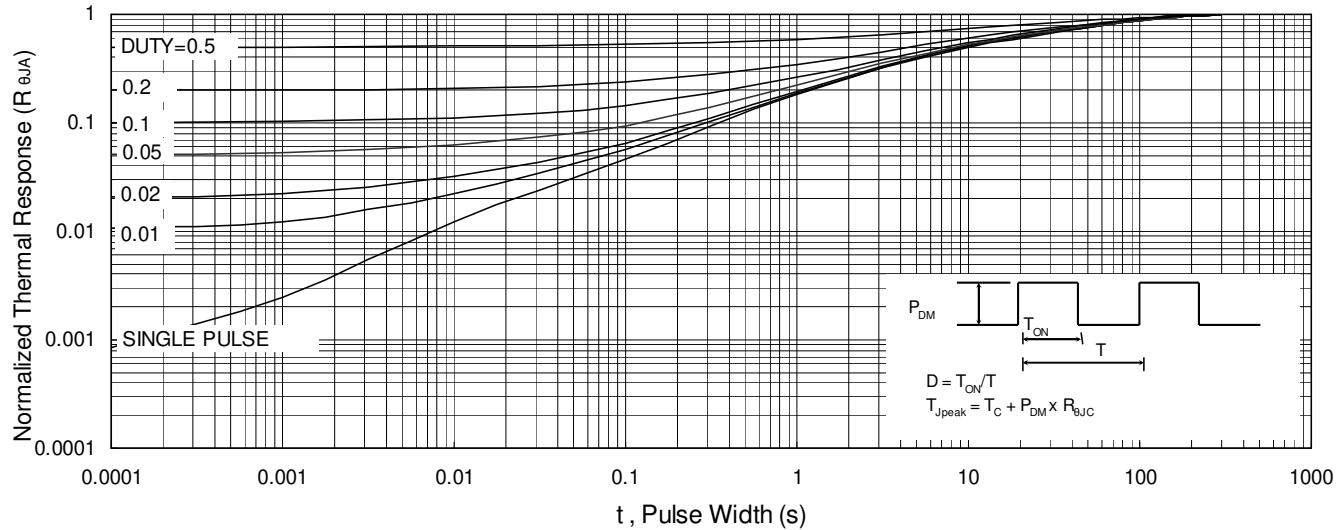
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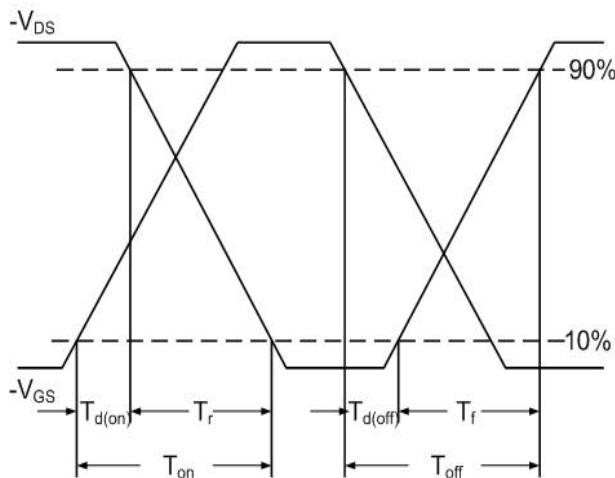
**Fig.7 Capacitance**



**Fig.8 Safe Operating Area**

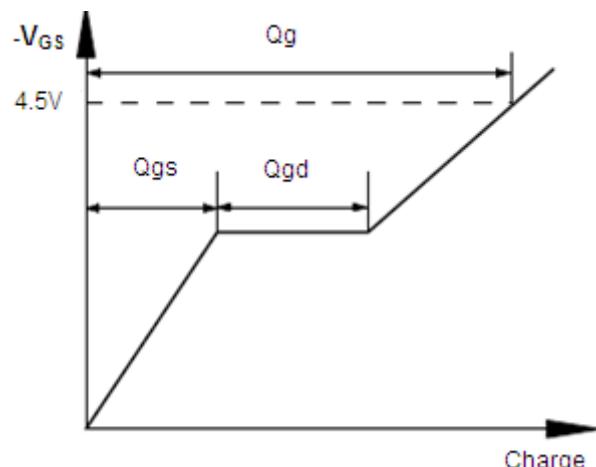


**Fig.9 Normalized Maximum Transient Thermal Impedance**



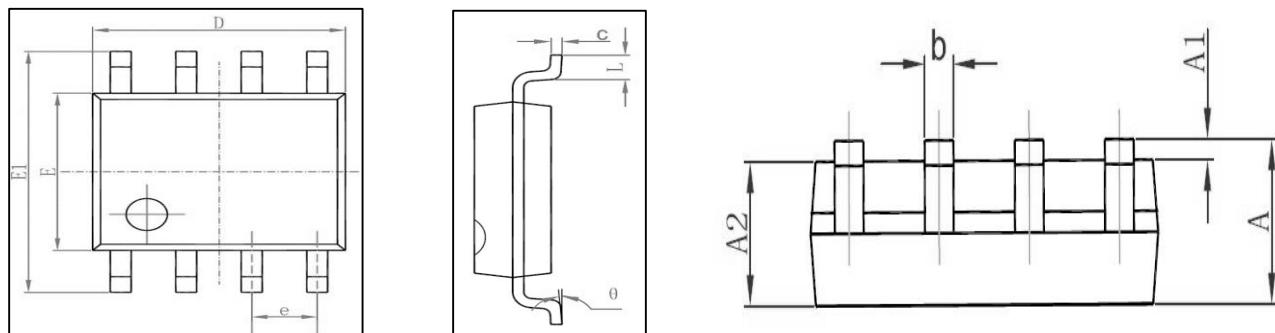
**Fig.10 Switching Time Waveform**

Data and specifications subject to change without notice.

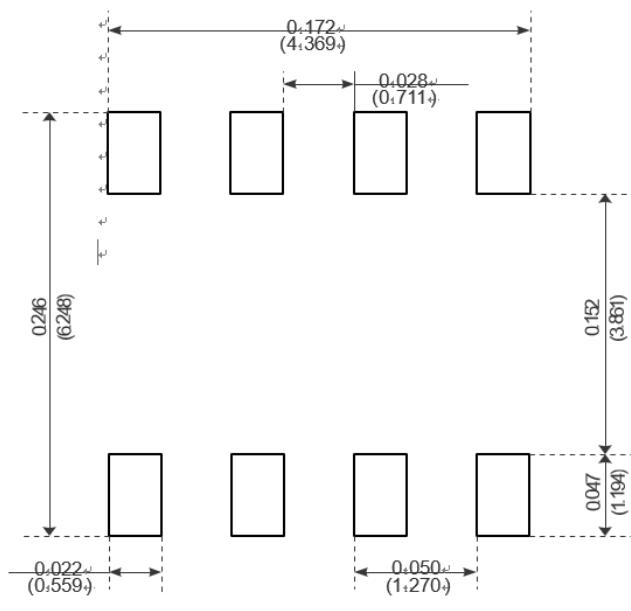


**Fig.11 Gate Charge Waveform**

## Package Mechanical Data:SOP-8L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°



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